RoHS

COMPLIANT

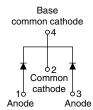
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Vishay Semiconductors



# Hyperfast Rectifier, 2 x 15 FRED Pt®





VS-30CTH02HN3

PRODUCT SUMMARY							
Package	TO-220AB						
I <sub>F(AV)</sub>	2 x 15 A						
$V_R$	200 V						
V <sub>F</sub> at I <sub>F</sub>	0.78 V						
t <sub>rr</sub> typ.	See Recovery table						
T <sub>J</sub> max.	175 °C						
Diode variation	Common cathode						

#### **FEATURES**

- Hyperfast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- · Low leakage current
- Fully isolated package (V<sub>INS</sub> = 2500 V<sub>RMS</sub>)
- Designed and qualified according to JEDEC®-JESD 47
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **DESCRIPTION / APPLICATIONS**

200 V series are the state of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Peak repetitive reverse voltage		$V_{RRM}$		200	V				
Average rectified forward current	per diode		T <sub>C</sub> = 159 °C	15	А				
Average rectilled forward current	per device	I <sub>F(AV)</sub>		30					
Non-repetitive peak surge current		I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	200					
Operating junction and storage temperatures		T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C				

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	200	-	-				
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 15 A	-	0.92	1.05	V			
		I <sub>F</sub> = 15 A, T <sub>J</sub> = 125 °C	-	0.78	0.85				
Reverse leakage current	I <sub>R</sub>	$V_R = V_R$ rated	-	-	10				
		$T_J = 125  ^{\circ}C$ , $V_R = V_R$ rated	-	5	300	μΑ			
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	-	57	-	pF			
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	ı	8	-	nH			



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>C</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time		$I_F = 1 A, dI_F/dt = 50$	$A/\mu s$ , $V_R = 30 V$	-	-	35			
		$I_F = 1 A, dI_F/dt = 100$	-	-	30	no			
	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	26	-	ns		
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 15 A	-	40	-			
Dook recovery ourrent	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	dl <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 160 V	-	2.8	-	Λ		
Peak recovery current		T <sub>J</sub> = 125 °C		-	6.0	-	А		
Reverse recovery charge	0	T <sub>J</sub> = 25 °C		=	37	-	200		
	$Q_{rr}$	T <sub>J</sub> = 125 °C		-	120	-	nC		

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range		T <sub>J</sub> , T <sub>Stg</sub>		-55	-	175	°C		
Thermal resistance, junction to case	per diode	R <sub>thJC</sub>	Mounting surface, flat, smooth, and greased	-	-	1.1	°C/W		
				-	2	-	g		
Approximate weight				-	0.07	-	oz.		
Mounting torque				6	-	12	kgf · cm		
				5	-	10	(lbf · cm)		
Marking device			Case style TO-220AB	30CTH02H					

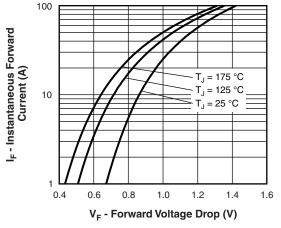


Fig. 1 - Typical Forward Voltage Drop Characteristics

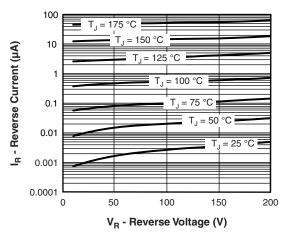


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

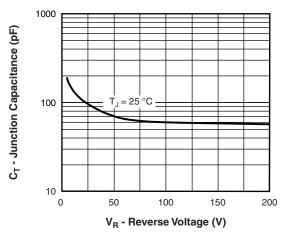


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

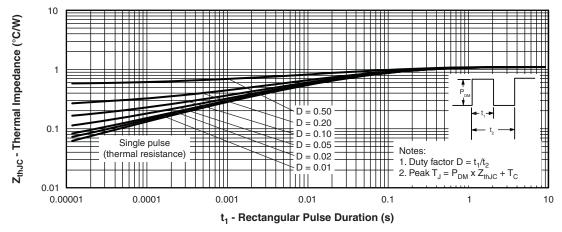


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

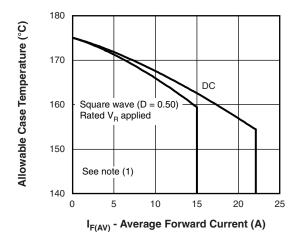


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

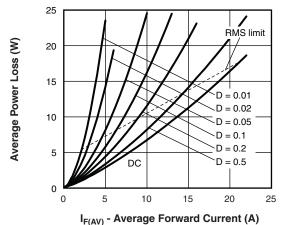


Fig. 6 - Forward Power Loss Characteristics

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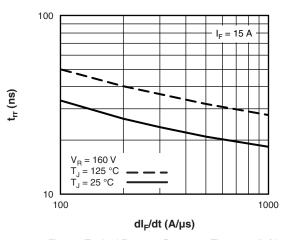


Fig. 7 - Typical Reverse Recovery Time vs.  $dI_{\text{F}}/dt$ 

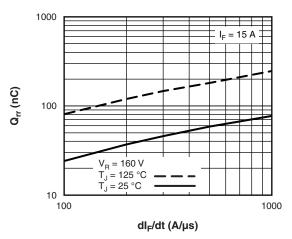
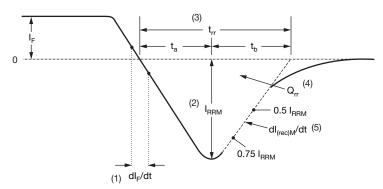


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{ll} \text{(1)} \ \ \text{Formula used:} \ T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \ \text{at} \ (I_{F(AV)}/D) \ (\text{see fig. 8}); \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \ (1 - D); \ I_R \ \text{at} \ V_{R1} = \text{rated} \ V_R \end{aligned}$ 



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  area under curve defined by  $t_{rr}$  and  $I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

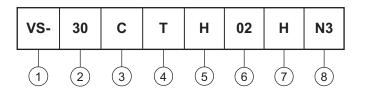
(5)  $dl_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 9 - Reverse Recovery Waveform and Definitions



### **ORDERING INFORMATION TABLE**

### **Device code**



Vishay Semiconductors product

2 - Current rating (30 = 30 A)

3 - C = common cathode

**4** - T = TO-220

5 - H = hyperfast recovery

6 - Voltage rating (02 = 200 V)

7 - H = AEC-Q101 qualified

8 - Environmental digit:

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

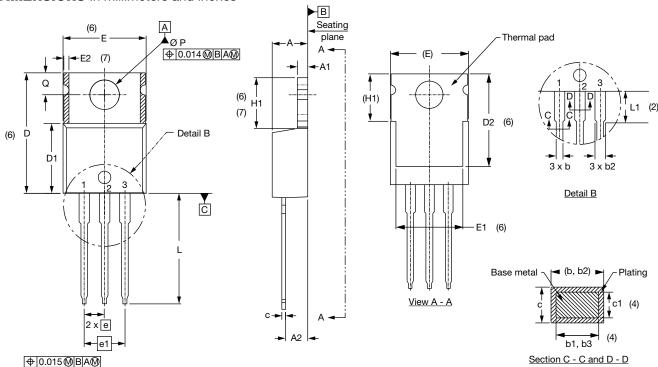
ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-30CTH02HN3	50	1000	Antistatic plastic tube					

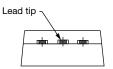
LINKS TO RELATED DOCUMENTS							
Dimensions TO-220AB <u>www.vishay.com/doc?95222</u>							
Part marking information	TO-220AB-N3	www.vishay.com/doc?95028					



### **TO-220AB**

#### **DIMENSIONS** in millimeters and inches





### Conforms to JEDEC® outline TO-220AB

SYMBOL	MILLIM	IETERS	INC	HES	NOTES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183			D2	11.68	12.88	0.460	0.507	6
A1	1.14	1.40	0.045	0.055			Е	10.11	10.51	0.398	0.414	3, 6
A2	2.56	2.92	0.101	0.115			E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040			E2	-	0.76	-	0.030	7
b1	0.38	0.97	0.015	0.038	4		е	2.41	2.67	0.095	0.105	
b2	1.20	1.73	0.047	0.068			e1	4.88	5.28	0.192	0.208	
b3	1.14	1.73	0.045	0.068	4		H1	5.84	6.86	0.230	0.270	6, 7
С	0.36	0.61	0.014	0.024			L	13.52	14.02	0.532	0.552	
c1	0.36	0.56	0.014	0.022	4		L1	3.32	3.82	0.131	0.150	2
D	14.85	15.25	0.585	0.600	3		ØР	3.54	3.73	0.139	0.147	
D1	8.38	9.02	0.330	0.355			Q	2.60	3.00	0.102	0.118	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline



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